

Amendments to the Specification:

Please replace the paragraph beginning at page 8, line 5, with the following rewritten paragraph:

a) A shown in FIG. 4a, a first plate 100 that is made of a silicon (Si) wafer has a thickness corresponding to the sum of the height of the top comb-type electrode 32 and the thickness of the stage 3, for example, a thickness of 100 μm . An etching mask layer 101 is formed on the surface of the plate 100. The etching mask layer 101 is formed of photoresist. In the etching mask layer 101, a part, excluding the region corresponding to the torsion bar 31 and the state 3 and the first frame layer 21 of the frame 2, surrounding the torsion bar and the state, i.e., a separate region 24a' corresponding to the separate region 24a, is removed by the etching process of a photolithography method, as shown in FIG. 5. Fig. 5 is a top view of the plate 100 at the step shown in FIG. 4a and having a mask layer 101 formed on the top surface of the plate 100. The reference numerals 31, 3, and 21 in FIG. 5 respectively represent the areas corresponding to the torsion bar, stage and first frame layer of the frame surrounding the stage. The latter figure shows the reference numbers of the torsion bar 31, the stage 3, and the first frame layer of the frame surrounding them so that the pattern of the etching mask layer can be easily understood.

Please replace the paragraph beginning at page 6, line 9, with the following rewritten paragraph:

Referring to FIG. 1, a frame 2 in the shape of a rectangular border is situated on a base plate 1 that is made of Pyrex PYREX® glass material, etc. and a stage 3 is positioned inside the frame 2. The stage is supported by a torsion bar 31 that is connected to the frame 2 and extends to the middle part of two ends of the frame 2 which face each other.

Please replace the paragraph beginning at page 10, line 7, with the following rewritten paragraph:

a) As shown in FIG. 6a, a metal layer 201 for forming signal lines is deposited on top of the base plate 1 made of Pyrex PYREX® glass material, etc., with the thickness of 500 µm. The metal layer 201 is used in adhering to Au wires and is thus preferably formed with Au. Here, the plate 1 is the base plate 1 that supports the total micro-actuator shown in FIGS. 2 and 3.

Please replace the paragraph beginning at page 11, line 18, with the following rewritten paragraph:

a) As shown in FIG. 7d, the second plate 300 and the base plate 1 made of Pyrex PYREX® glass material, etc., are bonded together with an anodic bonding process by applying heat, pressure and voltage.